

M3x0.5 THREADED INSERT (2X)

DATE CODE, MOLEX, PART NUMBER

NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.  
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE IEC NO: UCP2013-1884 DRAWN BY: IBARRA CHKD: MILLER APPR: MILLER DATE: 2012/11/12 DESCRIPTION: 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	CHECKED BY DATE	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
		2 PLACES ± 0.25 ± ---	DSCHM1DG 02/06/27			
		1 PLACE ± --- ± ---	CHECKED BY DATE			
		0 PLACE ± ±	DSCHM1DG 2003/03/18			
		ANGULAR ± 2 °	APPROVED BY DATE			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MBANK1S 2/18/03			
			MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			SEE TABLE	SD-75126-001	1 OF 3	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING OPTION	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-1003	75018-3021	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-1103	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-3003	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-7103	75018-8121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	WELDLESS

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

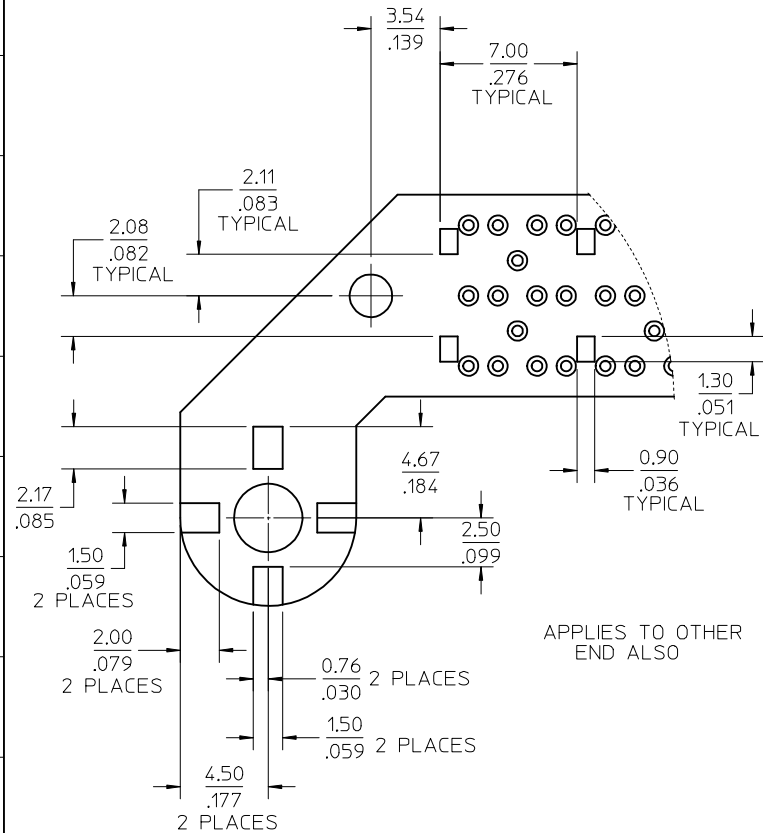
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: JORDWNTIBARRA CHKD: APPRS: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.010				
	▽=0	2 PLACES ±0.25				
		1 PLACE ±.010				
		0 PLACE ±				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			MATERIAL NO.	DOCUMENT NO.		SHEET NO.
			SEE TABLE	SD-75126-001		2 OF 3
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

PLATEAU HS DOCK INTERPOSER SALES DRAWING



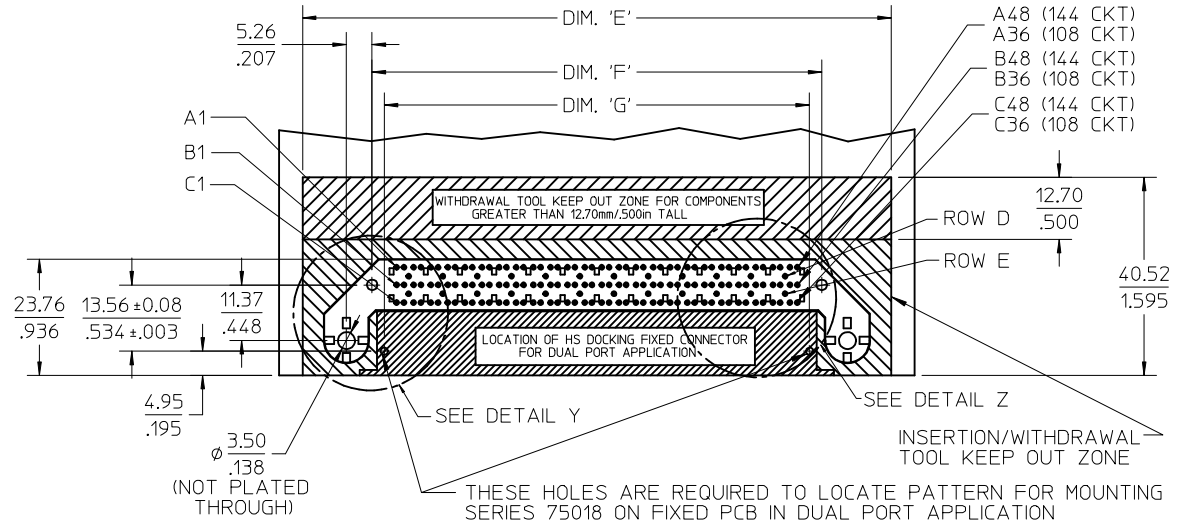
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



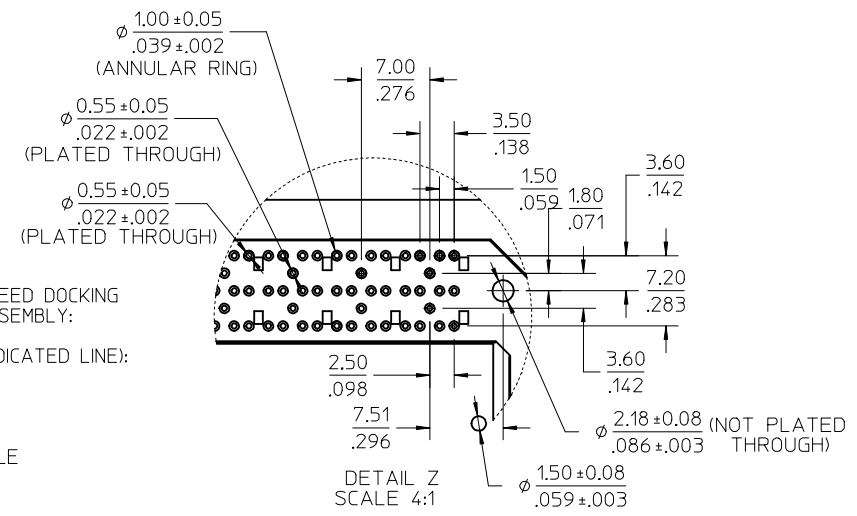
DETAIL Y  
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



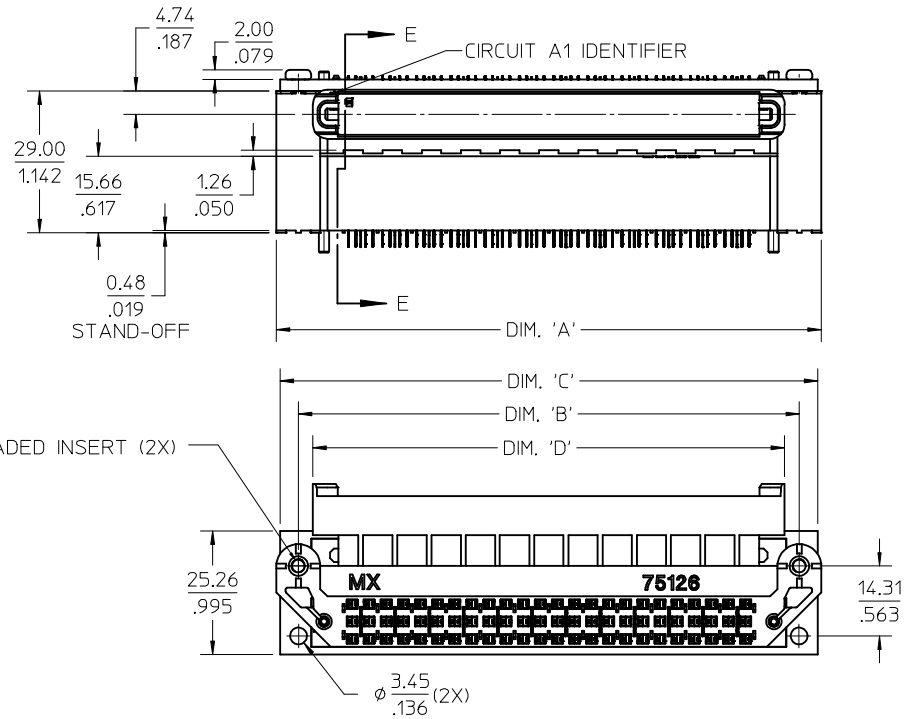
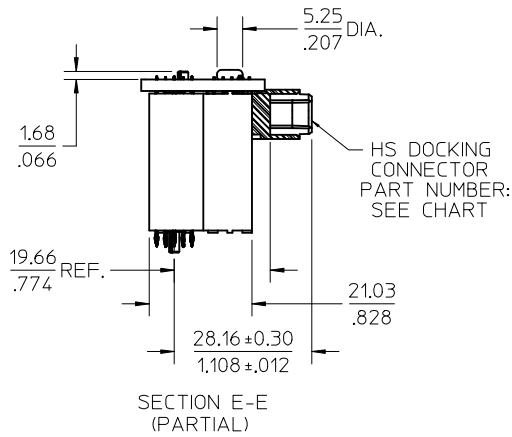
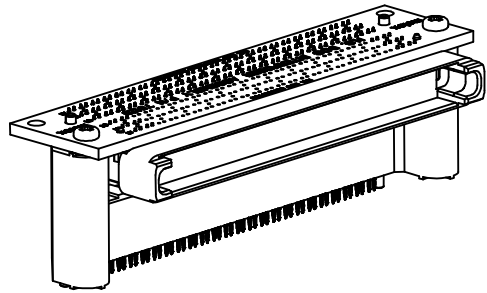
THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



DETAIL Z  
SCALE 4:1

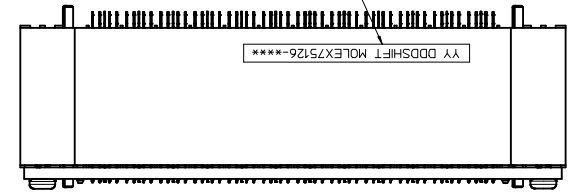
CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:  
 POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
 A2-A1: POWER/RETURN;  
 A4-A3: POWER/RETURN;  
 C2-C1: POWER/RETURN  
 ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
 CURRENT CAPACITY: 300mA  
 GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN: TIBARRA 2012/11/12 CHKO: APPR: SKILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	DSCMIDG 02/06/12	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			
	1 PLACE ± --- ± ---	DSCMIDG 2003/03/18	SD-75126-001			
	0 PLACE ± ±	APPROVED BY DATE	SHEET NO.			
		MBANKIS 2/18/03	3 OF 3			
			MATERIAL NO.			
			SEE TABLE			
			SIZE			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



M3x0.5 THREADED INSERT (2X)

DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.  
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE IEC NO: UCP2013-1884 DRAWN: IBARRA 2012/11/12 CHKD: MILLER APPR: MILLER 2013/01/04 DESCRIPTION:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	02/06/27	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	DATE	DATE			
	1 PLACE ± --- ± ---	DATE	DATE			
	0 PLACE ± ±	DATE	DATE			
	ANGULAR ± 2 °	MATERIAL NO.	DOCUMENT NO.			SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-75126-001			1 OF 3
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING OPTION	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-1003	75018-3021	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-1103	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-3003	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-7103	75018-8121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	WELDLESS

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

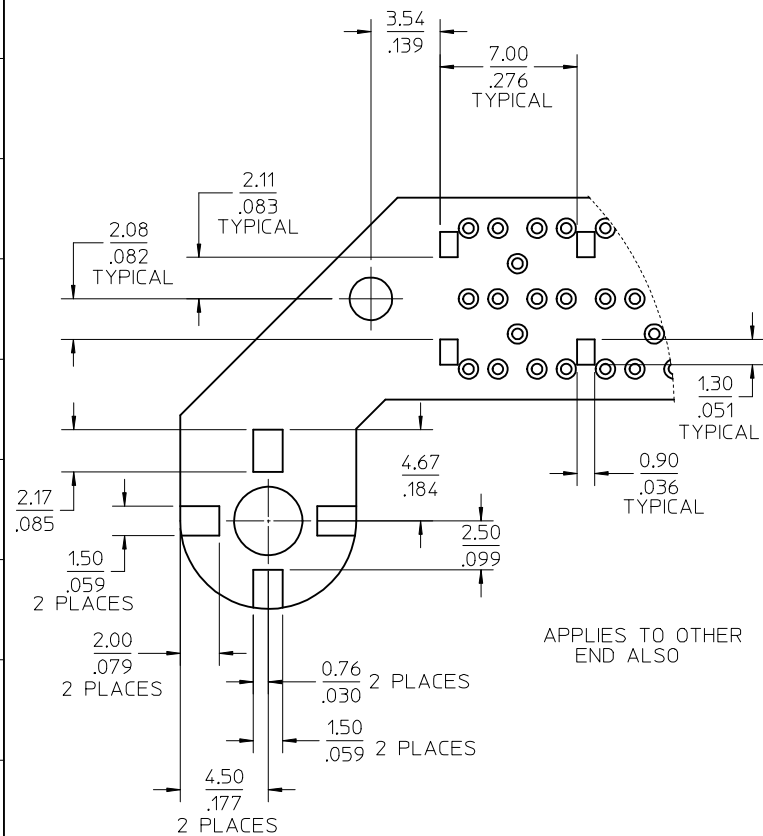
SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: JORDWNTIBARRA CHKD: APPRS: MILLER 2012/11/12 2003/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.010				
	▽=0	2 PLACES ±0.25				
		1 PLACE ±.010				
		0 PLACE ±				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			MATERIAL NO.	DOCUMENT NO.		
			SEE TABLE	SD-75126-001		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

PLATEAU HS DOCK INTERPOSER SALES DRAWING

molex

SHEET NO. 2 OF 3

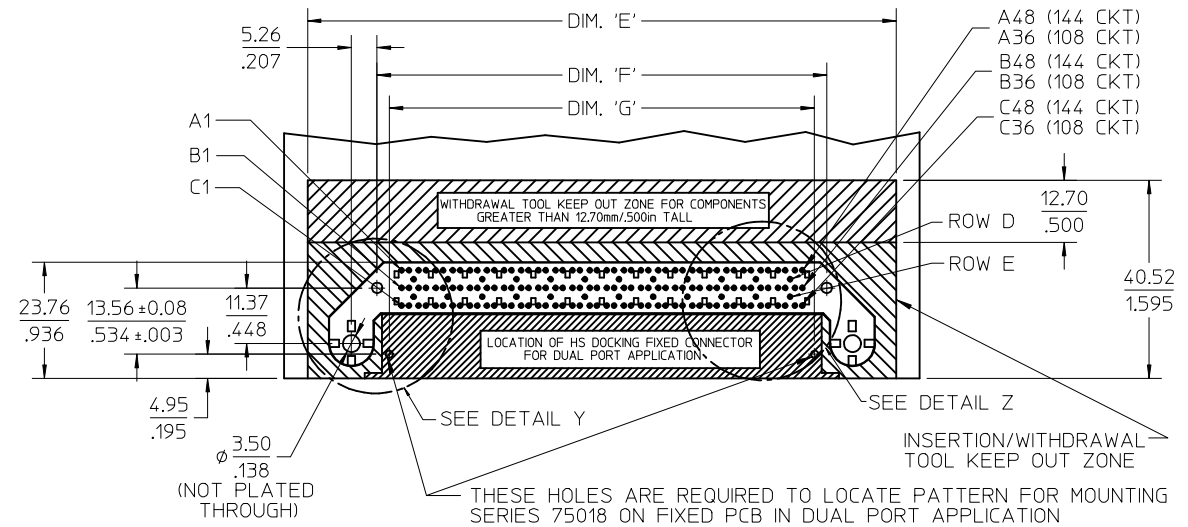
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



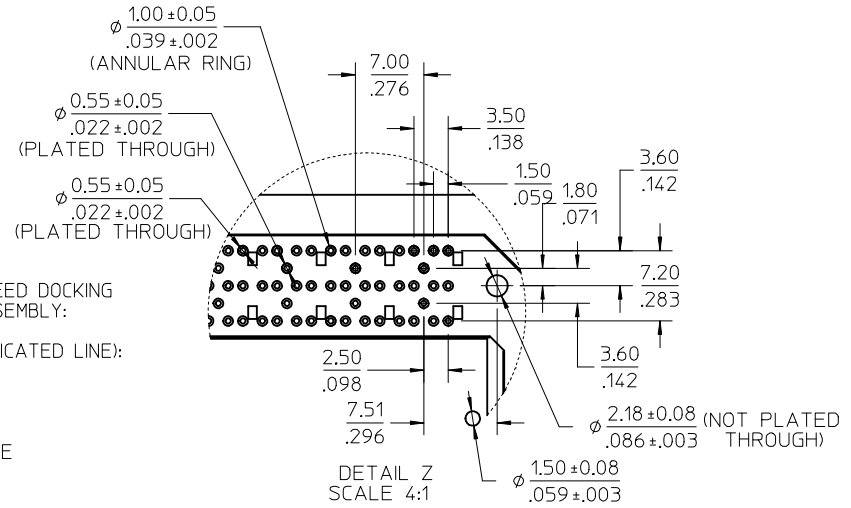
DETAIL Y  
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



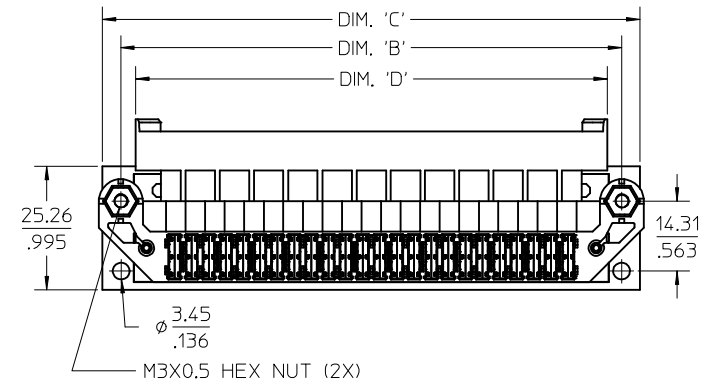
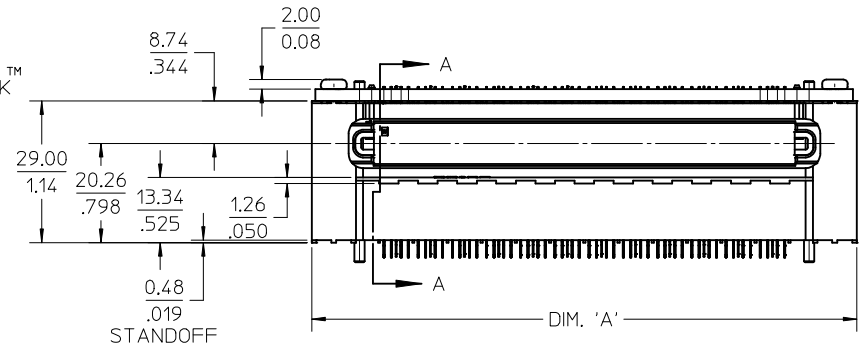
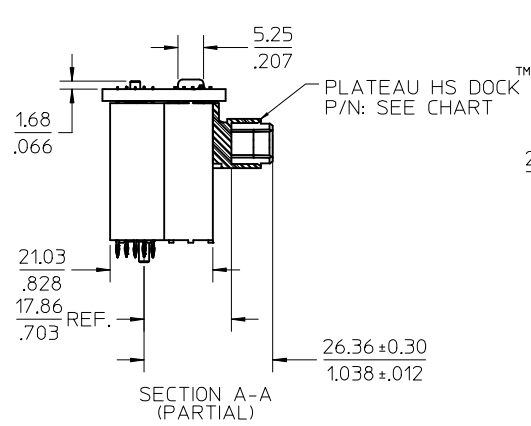
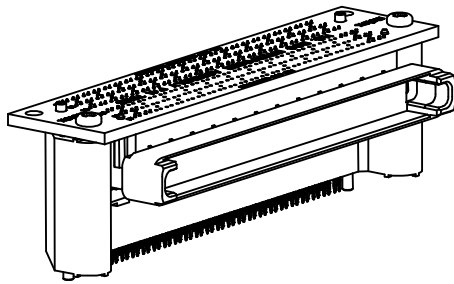
DETAIL Z  
SCALE 4:1

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:  
 A2-A1: POWER/RETURN;  
 A4-A3: POWER/RETURN;  
 C2-C1: POWER/RETURN

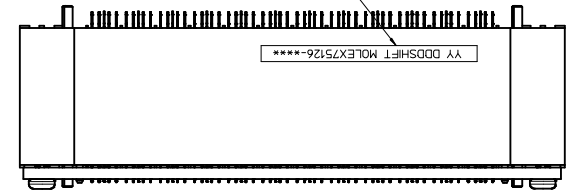
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
 CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN: TIBARRA 2012/11/12 CHKO: APPR: SKILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	DSCMIDG 02/06/127	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			SHEET NO.
	1 PLACE ± --- ± ---	APPROVED BY DATE	SD-75126-001			3 OF 3
	0 PLACE ± ±	MBANKIS 2/18/03	MATERIAL NO.			
			SEE TABLE			
			SIZE			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.  
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL THREADED INSERT: CARBON STEEL  
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EEC NO: UCP2013-1884 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER REV:	2012/11/12 2013/01/04	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED): <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>±.05</td> <td>±.001</td> </tr> <tr> <td>3 PLACES</td> <td>±.025</td> <td>±.001</td> </tr> <tr> <td>2 PLACES</td> <td>±.025</td> <td>±.001</td> </tr> <tr> <td>1 PLACE</td> <td>±.025</td> <td>±.001</td> </tr> <tr> <td>0 PLACE</td> <td>±.025</td> <td>±.001</td> </tr> </table>		mm	INCH	4 PLACES	±.05	±.001	3 PLACES	±.025	±.001	2 PLACES	±.025	±.001	1 PLACE	±.025	±.001	0 PLACE	±.025	±.001	DIMENSION STYLE MM/IN	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																						
	4 PLACES	±.05	±.001																						
	3 PLACES	±.025	±.001																						
2 PLACES	±.025	±.001																							
1 PLACE	±.025	±.001																							
0 PLACE	±.025	±.001																							
DRAWN BY: KSTILES DATE: 7/16/2003 CHECKED BY: DATE: 7/16/2003 DSCHMIDG APPROVED BY: DATE: 7/16/2003 MBANKIS			TITLE <b>PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING</b>		<b>molex</b>																				
MATERIAL NO. DOCUMENT NO.			SEE TABLE		SD-75126-002		SHEET NO. 1 OF 3																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																									

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

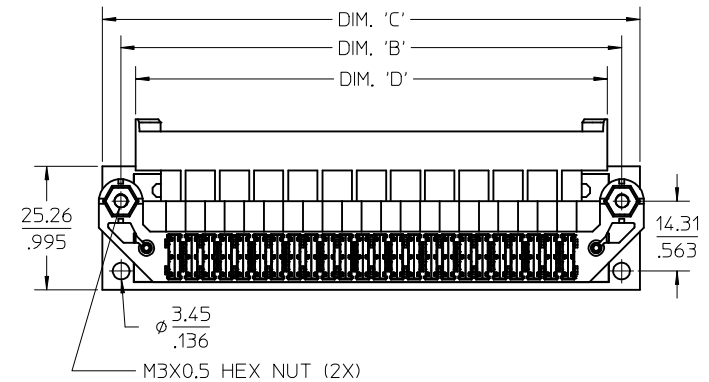
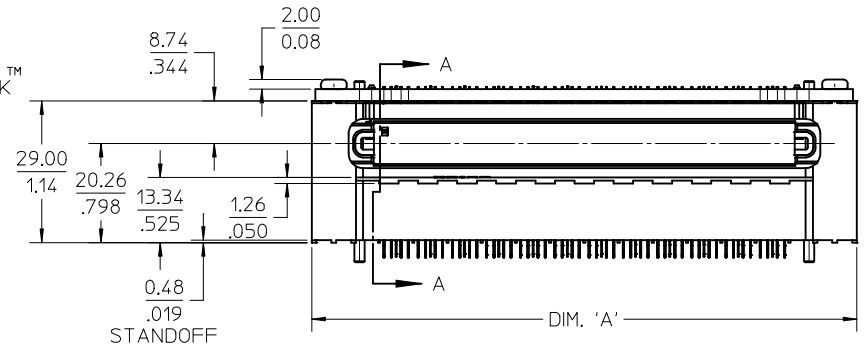
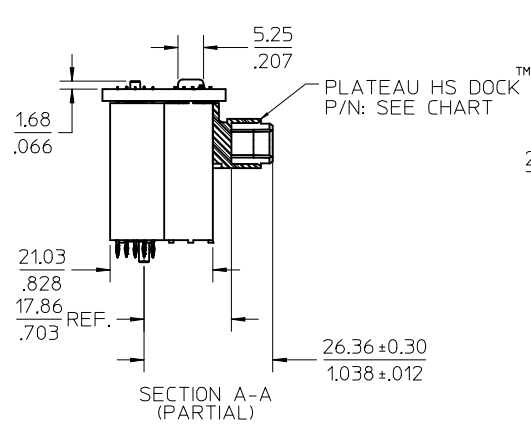
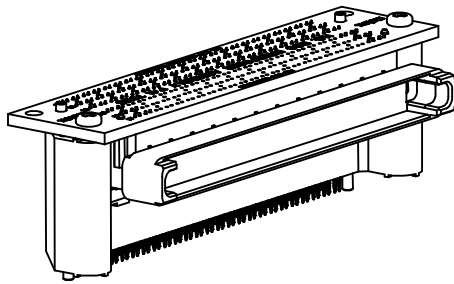
HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

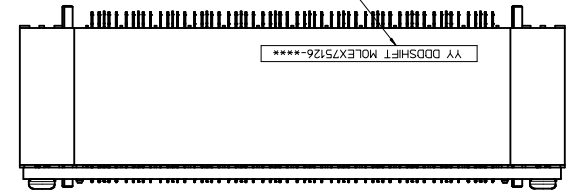
SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKD: J. BARRA APPR: SMILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°	DRAWN BY DATE	TITLE		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	KSTILES 7/16/2003	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING		
			CHECKED BY DATE	molex		
			DSCHMIDG 7/16/2003	SD-75126-002		
			APPROVED BY DATE	DOCUMENT NO.		
			MBANKIS 7/16/2003	2 OF 3		
			MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SEE TABLE			







DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.  
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL THREADED INSERT: CARBON STEEL  
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY: KSTILES DATE: 7/16/2003	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	3 PLACES ± --- ± .010	CHECKED BY: DSCHMIDG DATE: 7/16/2003	<b>molex</b> MATERIAL NO. DOCUMENT NO. SD-75126-002 SHEET NO. 1 OF 3		
	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	APPROVED BY: MBANKIS DATE: 7/16/2003	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	0 PLACE ± ±	ANGULAR ±1/2°	SIZE D			

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

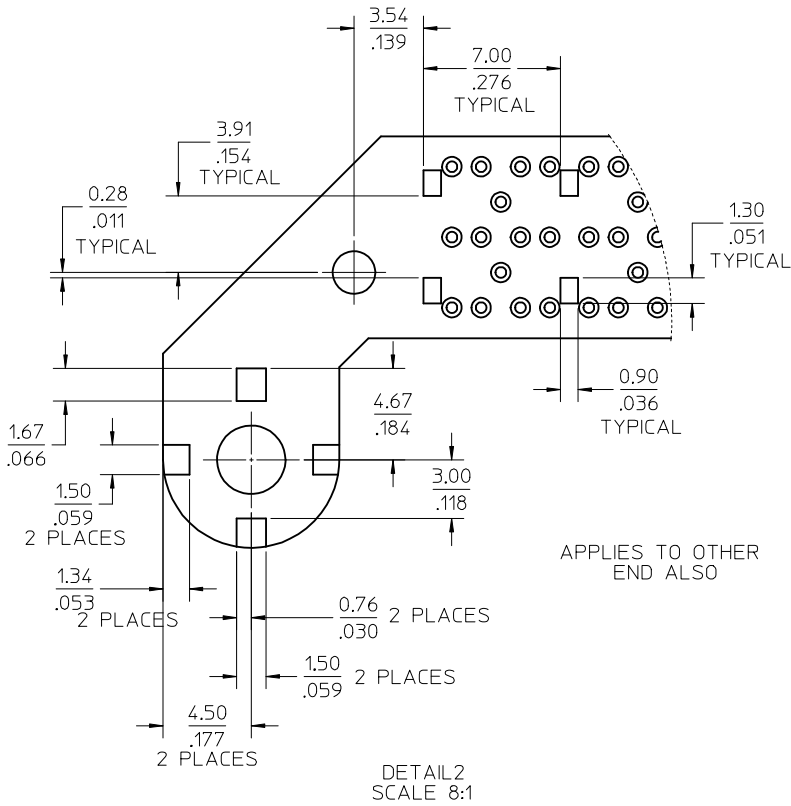
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKO: J. BARRA APPROX: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°	DRAWN BY: KSTILES	DATE: 7/16/2003	TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY: DSCHMIDG	DATE: 7/16/2003	molex	
			APPROVED BY: MBANKIS	DATE: 7/16/2003	DOCUMENT NO. SD-75126-002	
			MATERIAL NO.	DATE: 7/16/2003	SHEET NO. 2 OF 3	
			SIZE: D		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

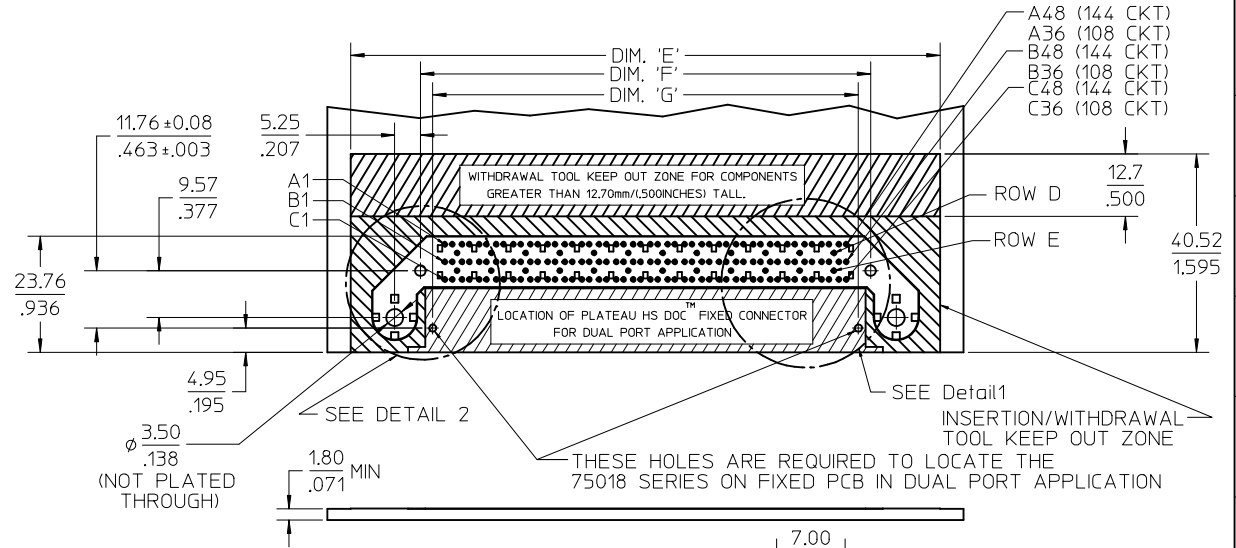
# KEEP OUT AREA FOR STAND-OFFS



APPLIES TO OTHER END ALSO

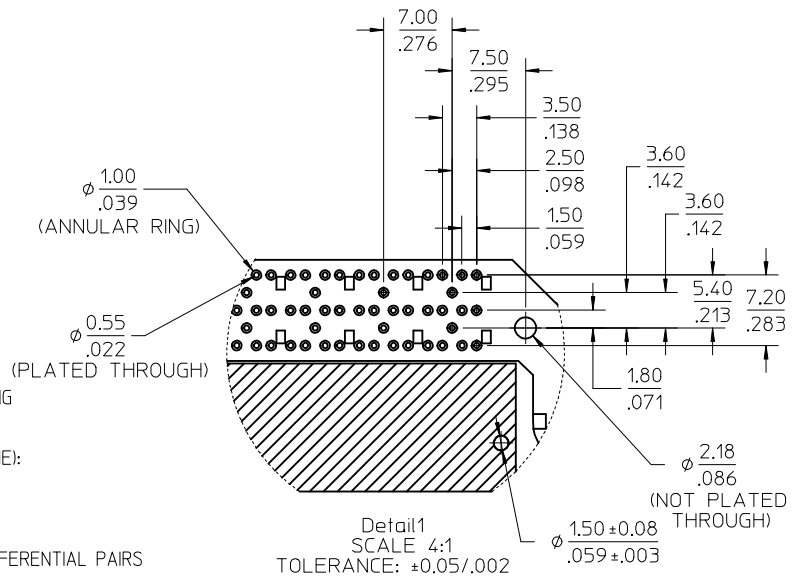
DETAIL2  
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.



SEE DETAIL 2  
 $\phi$  3.50 (.138)  
 (NOT PLATED THROUGH)

SEE Detail1  
 THESE HOLES ARE REQUIRED TO LOCATE THE 75018 SERIES ON FIXED PCB IN DUAL PORT APPLICATION



Detail1  
SCALE 4:1

TOLERANCE:  $\pm 0.051/.002$

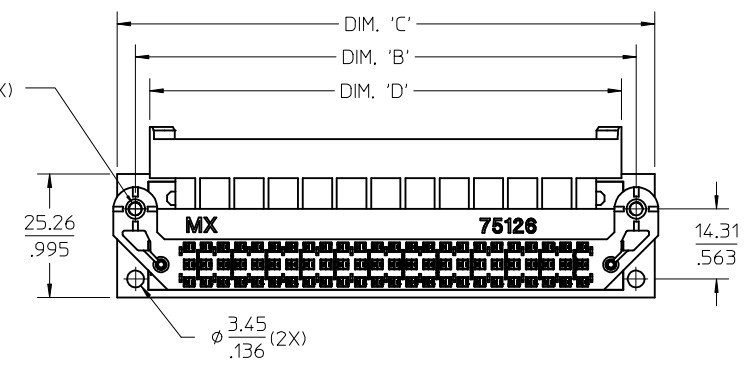
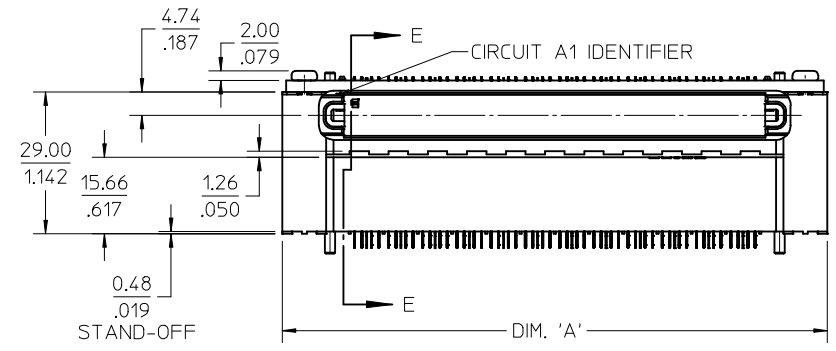
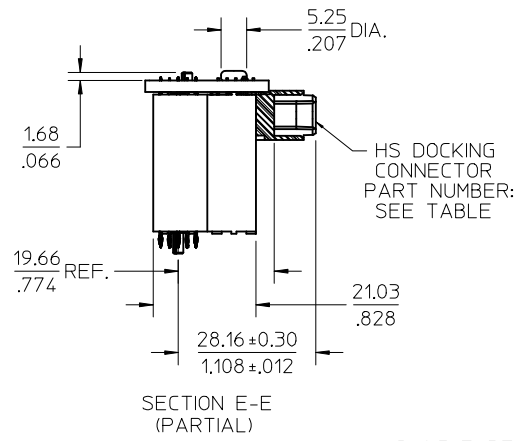
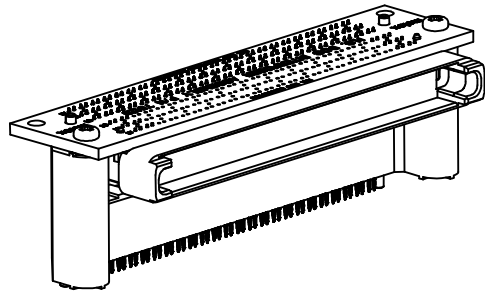
CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
 A2-A1: POWER/RETURN,  
 A4-A3: POWER/RETURN,  
 C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
 CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 IEC NO: UCP2013-1884 DRAWN: TIBARRA CHKO: 2002/11/12 APPROX: MILLER DESCRIPTION: 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$	mm INCH	MM/IN	2:1	METRIC	
	$\nabla=0$	4 PLACES $\pm$ --- $\pm$ ---	DRAWN BY DATE			
	$\nabla=0$	3 PLACES $\pm$ --- $\pm$ .010	CHECKED BY DATE			
	2 PLACES $\pm$ 0.25 $\pm$ ---	DSCHEMIDG DATE				PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING
	1 PLACE $\pm$ --- $\pm$ ---	APPROVED BY DATE				<b>molex</b>
	0 PLACE $\pm$ $\pm$ ---	MBANK IS DATE				SD-75126-002
		MATERIAL NO.	SEE TABLE			SHEET NO. 3 OF 3
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

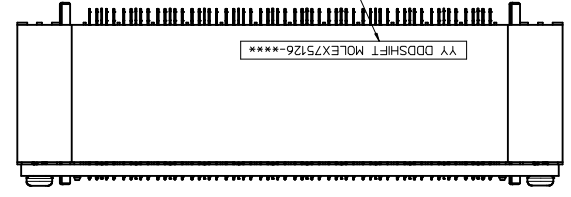


CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-7303	75018-5121	<u>111.50</u> 4.390	<u>102.50</u> 4.035	<u>110.00</u> 4.331	<u>96.62</u> 3.804	<u>120.40</u> 4.740	<u>92.00±0.08</u> 3.622±.003	<u>87.00±0.08</u> 3.425±.003	WELDLESS

- NOTES:
- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
 HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.  
 WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.  
 CONTACTS: COPPER ALLOY  
 HEXAGONAL THREADED INSERT: CARBON STEEL  
 MACHINE SCREW: CARBON STEEL
  - PLATING FINISH:  
 CONTACT INTERFACE  
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
 NICKEL UNDERPLATE OVERALL  
 COMPLIANT INTERFACE  
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
 NICKEL UNDERPLATE OVERALL  
 HOUSING  
 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
 COPPER UNDERPLATE OVERALL
  - THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
  - THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
  - THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
  - RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
  - USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
  - RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN, 5 IN-LBS MAX.

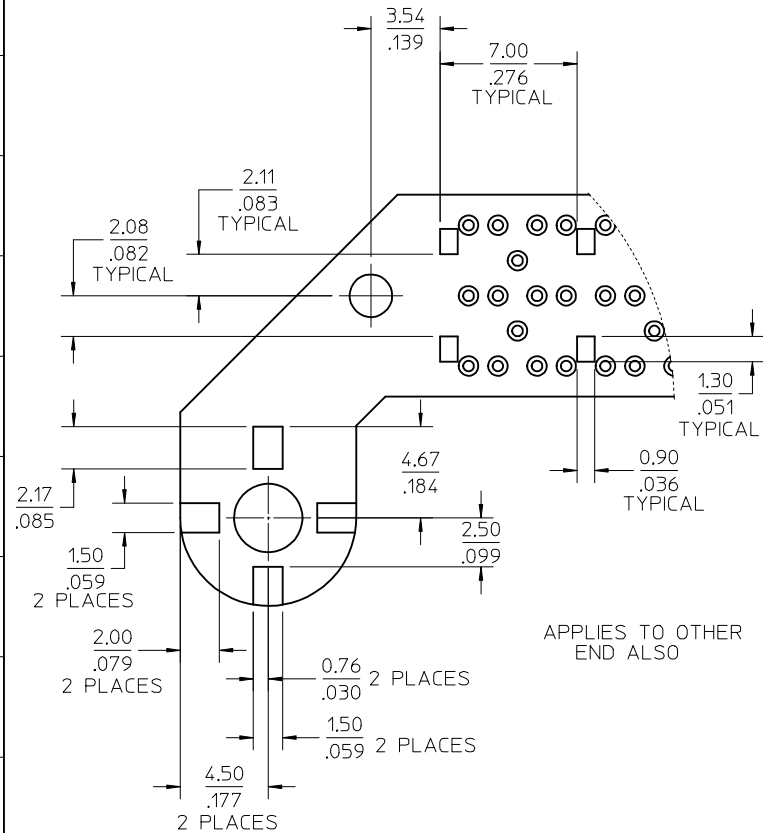
M3x0.5 THREADED INSERT (2X)

DATE CODE, MOLEX, PART NUMBER



INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYD BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	mm INCH	MM/IN	2:1	METRIC		
	▽=0	4 PLACES ± --- ± ---					
	▽=0	3 PLACES ± --- ± .010					
		2 PLACES ± 0.25 ± ---					
		1 PLACE ± --- ± ---					
		0 PLACE ± --- ± ---					
		ANGULAR ± 2 °					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
			MATERIAL NO.	DOCUMENT NO.			
			SEE TABLE	SD-75126-1000			
						SHEET NO. 1 OF 2	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

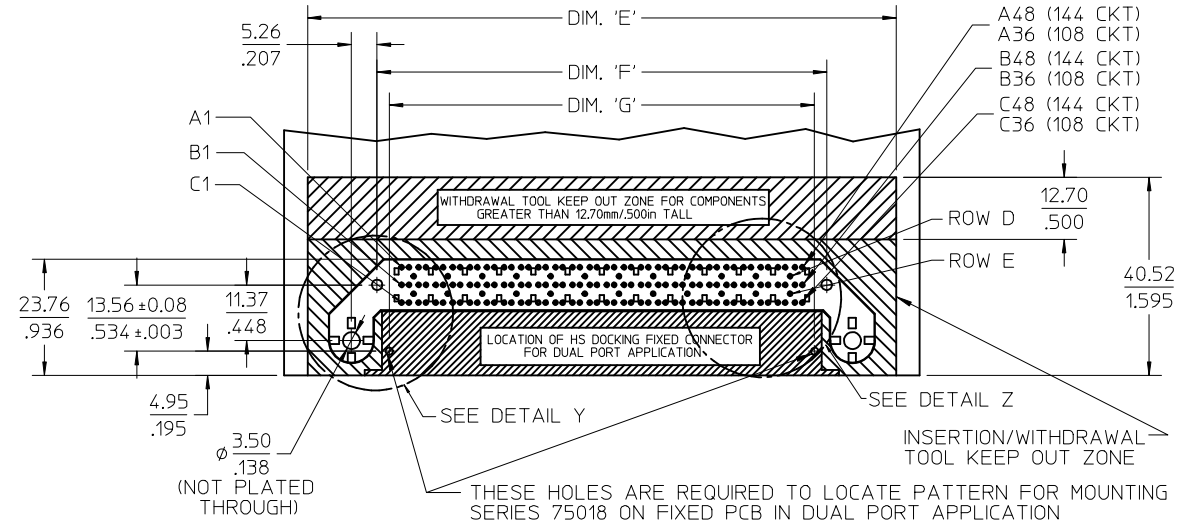
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



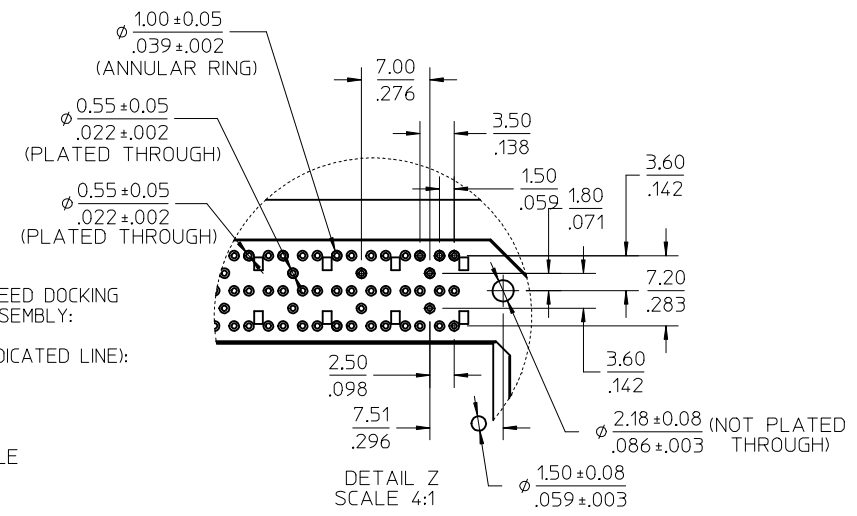
DETAIL Y  
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION

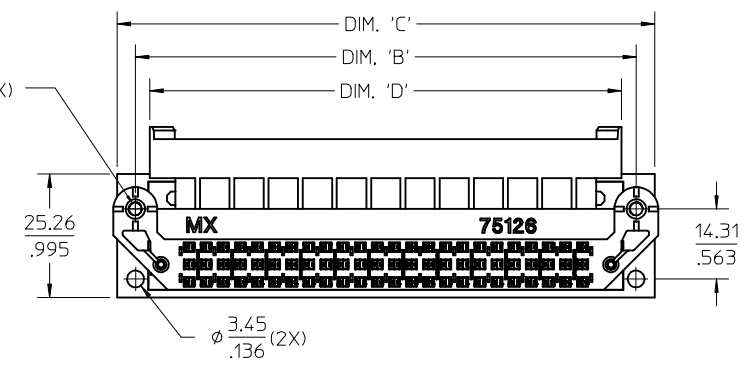
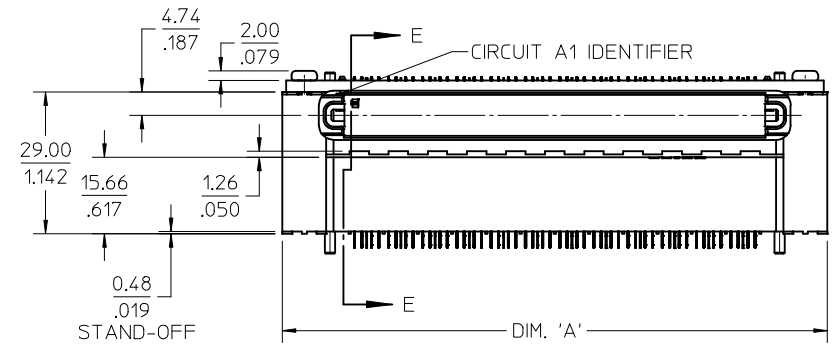
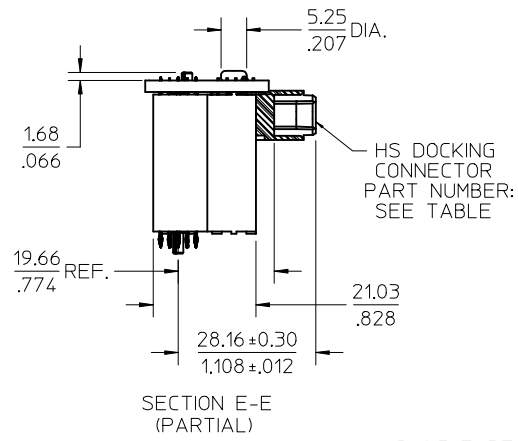
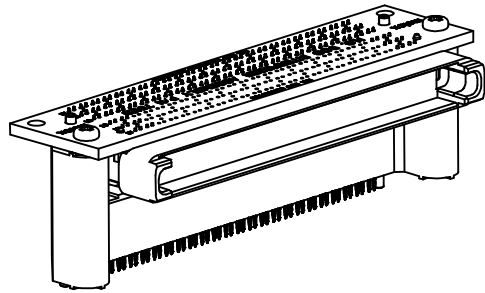


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:  
 POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
 A2-A1: POWER/RETURN;  
 A4-A3: POWER/RETURN;  
 C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
 CURRENT CAPACITY: 300mA

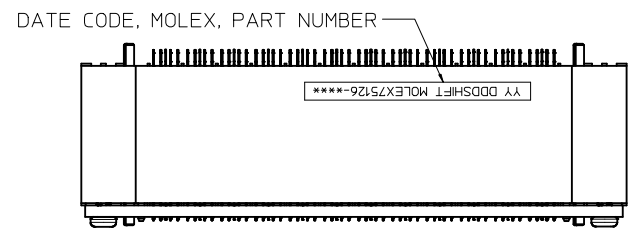
GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	TIBARRA 2014/02/13	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			SHEET NO.
	1 PLACE ± --- ± ---	BBARKER 2014/02/14	SD-75126-1000			2 OF 2
	0 PLACE ± --- ± ---	APPROVED BY DATE	MATERIAL NO.			
		SMILLER 2014/03/13	SEE TABLE			
			DRAFT WHERE APPLICABLE			
			MUST REMAIN WITHIN DIMENSIONS			
			SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



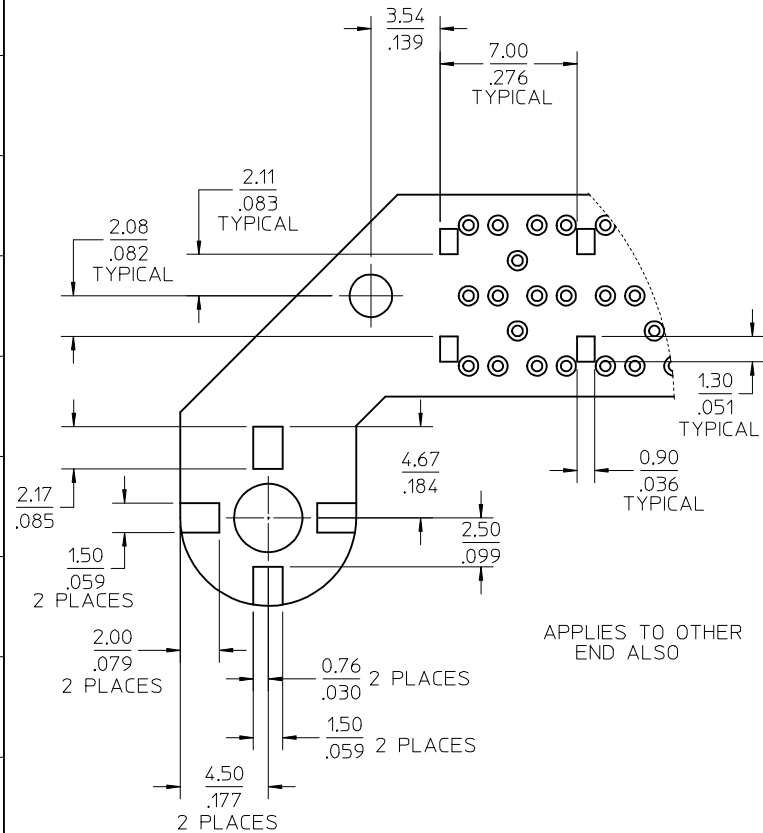
CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-7303	75018-5121	<u>111.50</u> 4.390	<u>102.50</u> 4.035	<u>110.00</u> 4.331	<u>96.62</u> 3.804	<u>120.40</u> 4.740	<u>92.00±0.08</u> 3.622±.003	<u>87.00±0.08</u> 3.425±.003	WELDLESS

- NOTES:
- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.  
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL THREADED INSERT: CARBON STEEL  
MACHINE SCREW: CARBON STEEL
  - PLATING FINISH:  
CONTACT INTERFACE  
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL  
COMPLIANT INTERFACE  
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL  
HOUSING  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL
  - THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
  - THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
  - THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
  - RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
  - USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
  - RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN, 5 IN-LBS MAX.



<b>INITIAL RELEASE</b> EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYD BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	<b>QUALITY SYMBOLS</b> ∇=0 ∇=0 ∇=0	<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b>		<b>DIMENSION STYLE</b> MM/IN	<b>SCALE</b> 2:1	<b>DESIGN UNITS</b> METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	mm      INCH	DRAWN BY: TIBARRA      DATE: 2014/02/13 CHECKED BY: BARKER      DATE: 2014/02/14 APPROVED BY: SMILLER      DATE: 2014/03/13	<b>TITLE</b> PLATEAU HS DOCK INTERPOSER SALES DRAWING		
		ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO: <b>SEE TABLE</b>	DOCUMENT NO: <b>SD-75126-1000</b>	SHEET NO. 1 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

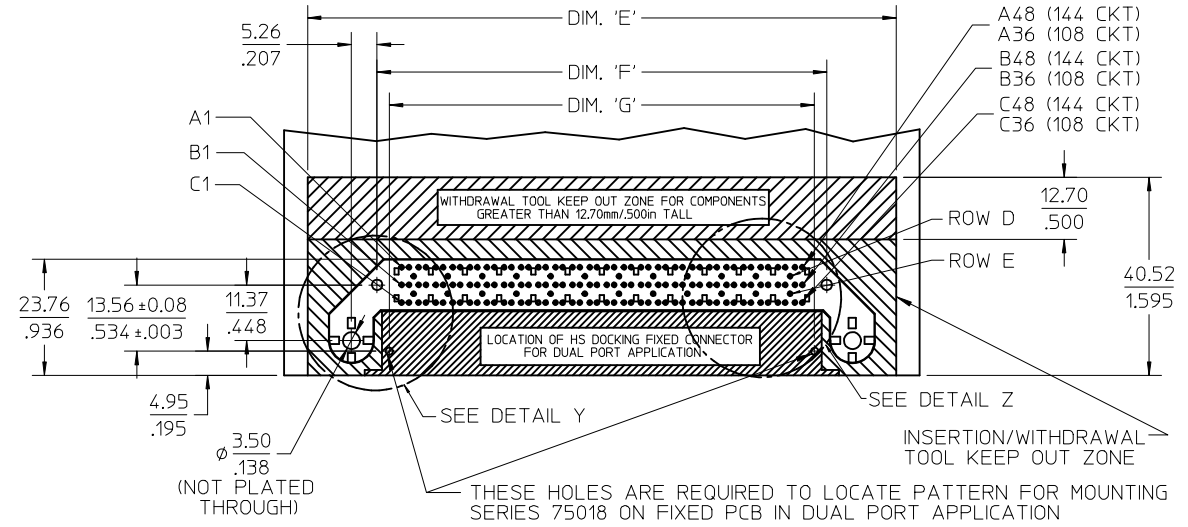
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



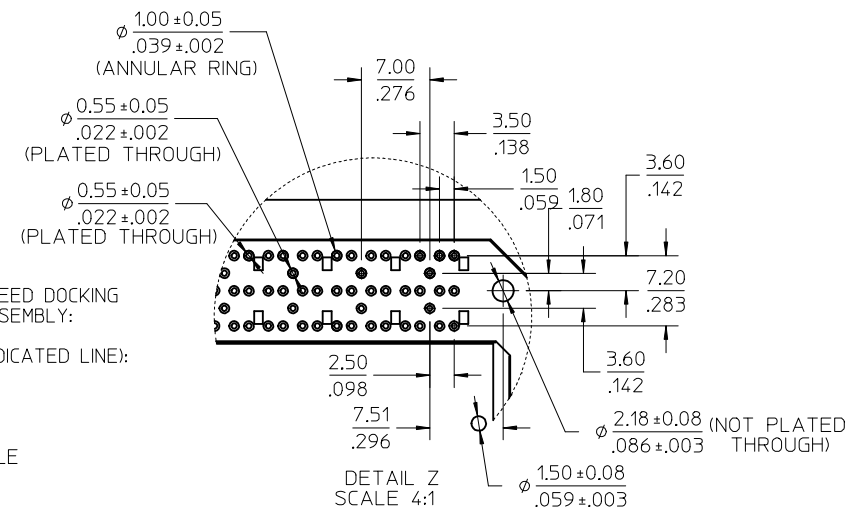
DETAIL Y  
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION

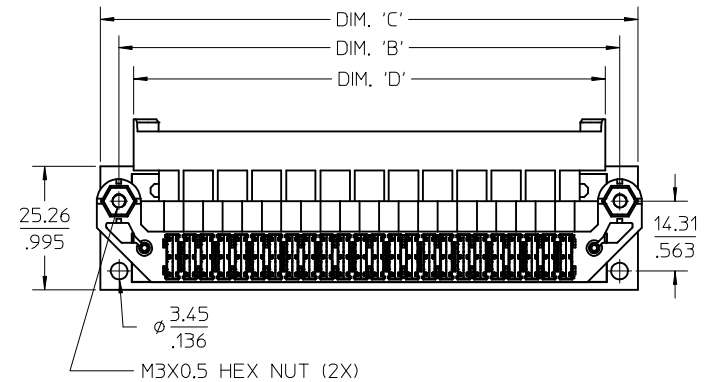
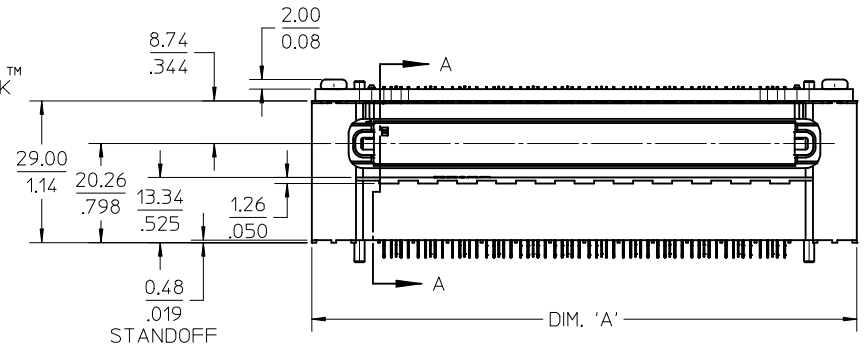
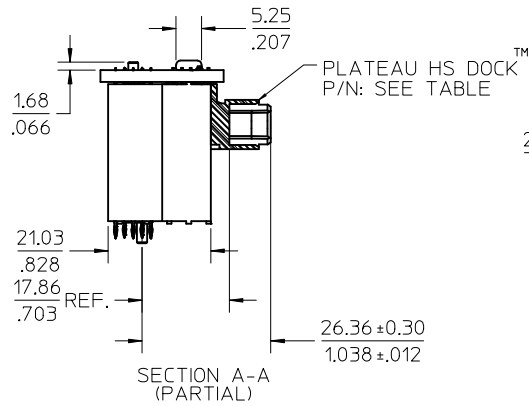
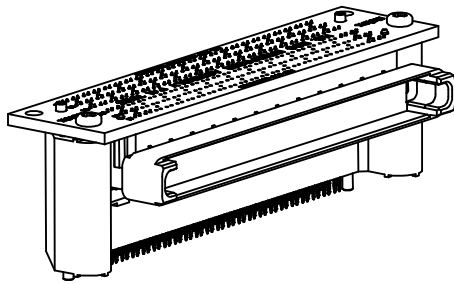


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:  
 POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
 A2-A1: POWER/RETURN;  
 A4-A3: POWER/RETURN;  
 C2-C1: POWER/RETURN

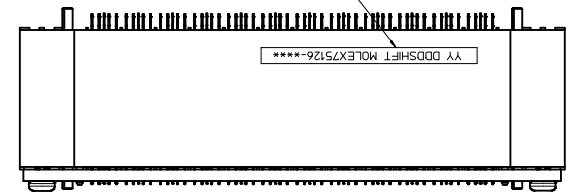
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
 CURRENT CAPACITY: 300mA  
 GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	TIBARRA 2014/02/13	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			SHEET NO.
	1 PLACE ± --- ± ---	BBARKER 2014/02/14	SD-75126-1000			2 OF 2
	0 PLACE ± --- ± ---	APPROVED BY DATE	MATERIAL NO.			
		SMILLER 2014/03/13	SEE TABLE			
			DRAFT WHERE APPLICABLE			
			MUST REMAIN WITHIN DIMENSIONS			
			SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			





DATE CODE, MOLEX, PART NUMBER



CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-8301	75018-5123	111.50 / 4.390	102.50 / 4.035	110.00 / 4.331	96.62 / 3.804	120.40 / 4.740	92.00±0.08 / 3.622±.003	87.00±0.08 / 3.425±.003	WELDLESS

NOTES:

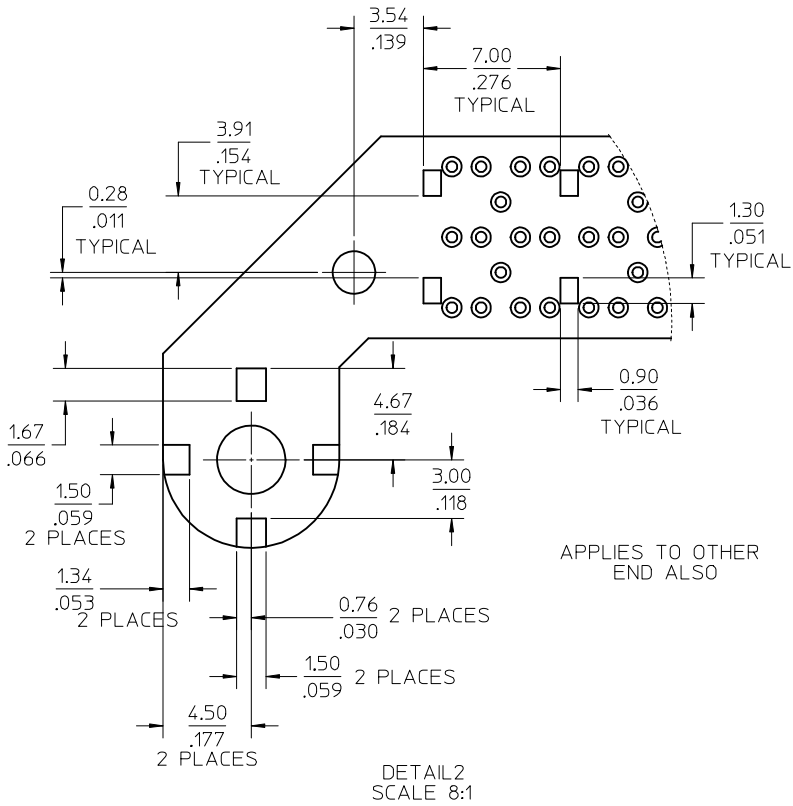
- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
 HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.  
 WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.  
 CONTACTS: COPPER ALLOY  
 HEXAGONAL THREADED INSERT: CARBON STEEL  
 MACHINE SCREW: CARBON STEEL
- PLATING FINISH:  
 CONTACT INTERFACE  
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
 NICKEL UNDERPLATE OVERALL  
 COMPLIANT INTERFACE  
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
 NICKEL UNDERPLATE OVERALL  
 HOUSING  
 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
 COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN.  
 TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHKD BY: BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	MM/IN	2:1	METRIC	☉
	▽=0	INCH				
	▽=0	4 PLACES ±.010 3 PLACES ±.025 2 PLACES ±.050 1 PLACE ±.100 0 PLACE ±.200				
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			SEE TABLE	SD-75126-2000	1 OF 2	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

PLATEAU HS DOCK  
8.74 CL INTERPOSER  
SALES DRAWING

**molex**

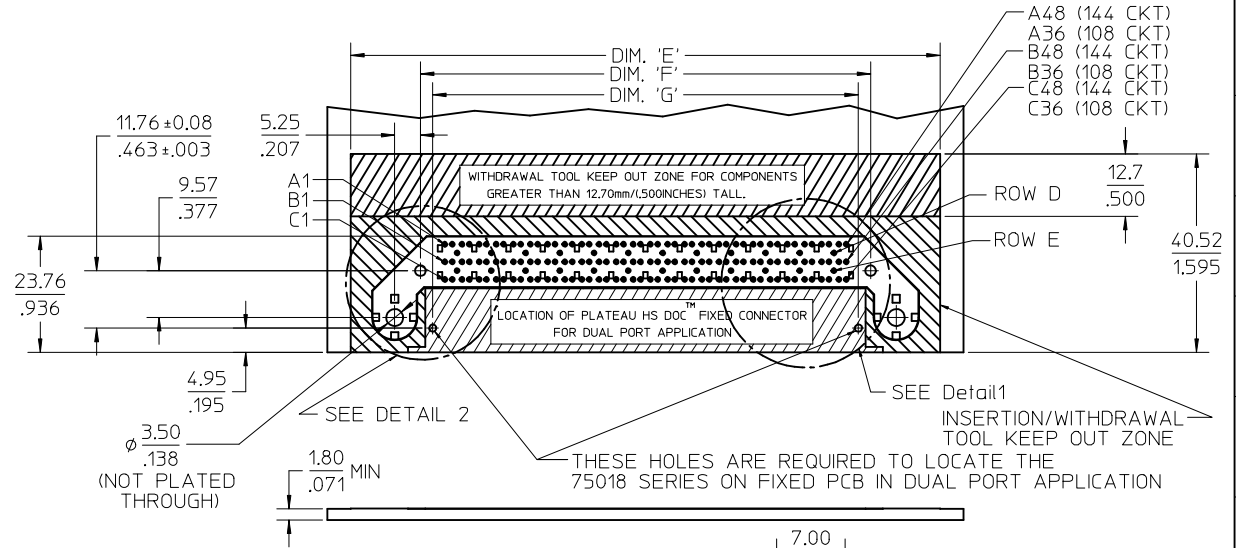
# KEEP OUT AREA FOR STAND-OFFS



DETAIL2  
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

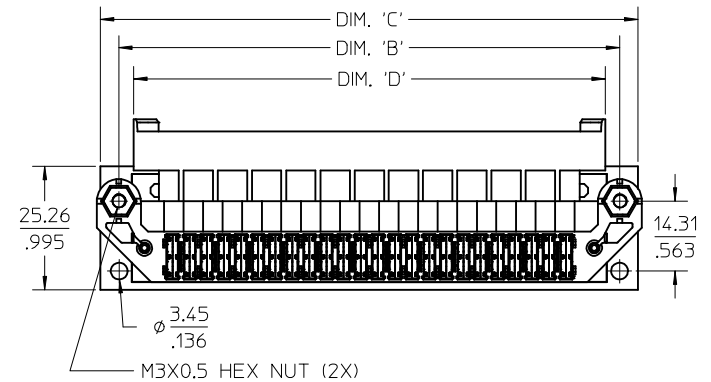
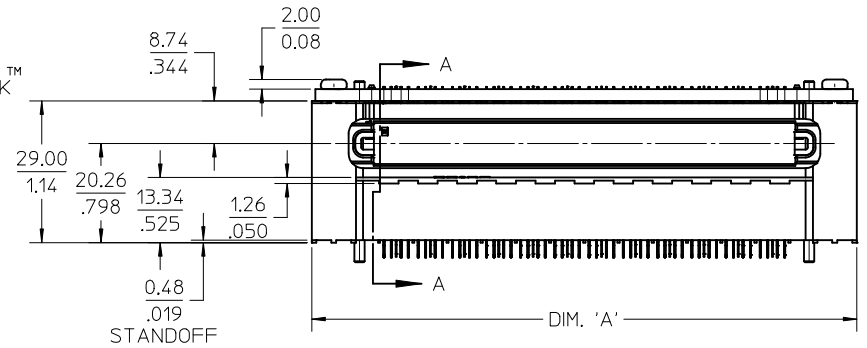
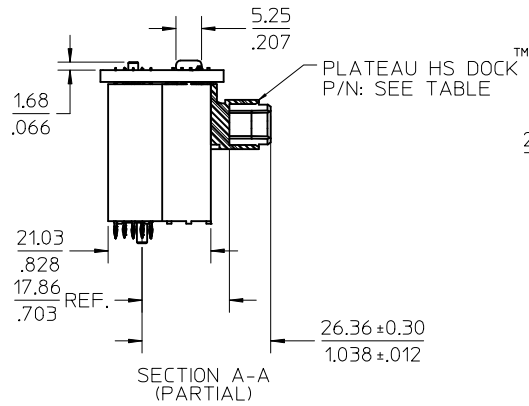
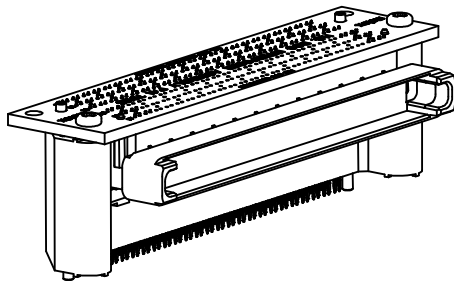
POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
A2-A1: POWER/RETURN,  
A4-A3: POWER/RETURN,  
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
CURRENT CAPACITY: 300mA

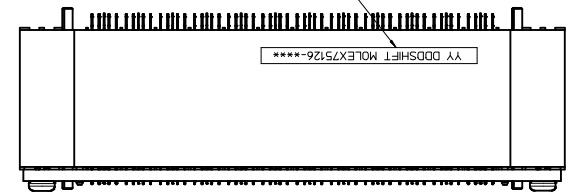
GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EC NO: UCP2014-3379 DRAWN BY: T1BARRA CHECKED BY: BBARKER APPROVED BY: SMILLER	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		mm	INCH	MM/IN	2:1	METRIC	☉	
		4 PLACES	± .010					PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING <b>molex</b>
		3 PLACES	± .025					
		2 PLACES	± .050					DOCUMENT NO. SD-75126-2000
		1 PLACE	± .100					
		0 PLACE	± .150					SHEET NO. 2 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		MATERIAL NO.		SIZE		
				SEE TABLE		D		

Detail1  
SCALE 4:1  
TOLERANCE: ±0.05/.002



DATE CODE, MOLEX, PART NUMBER



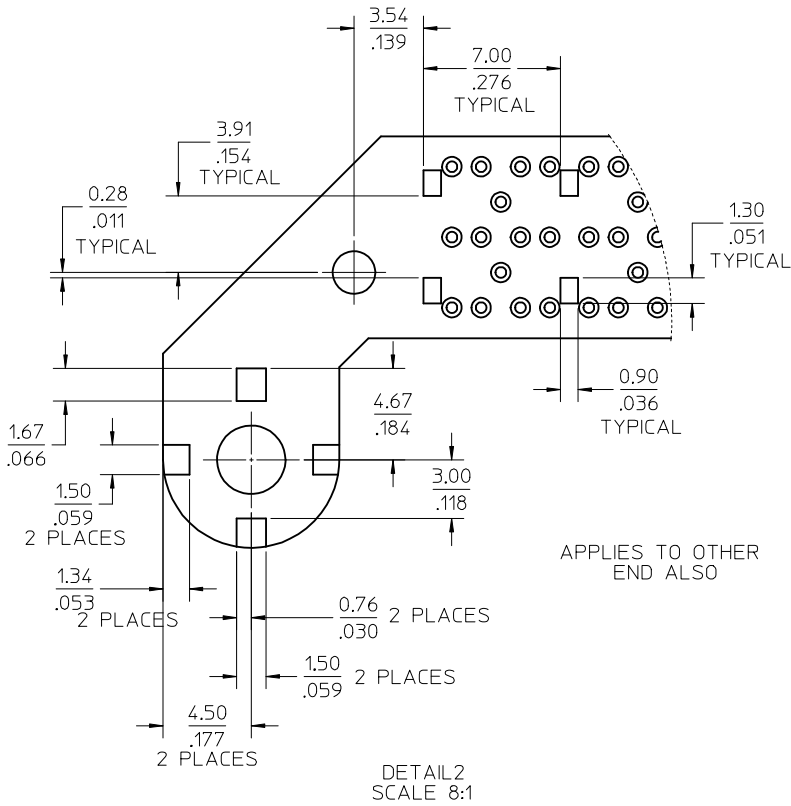
CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-8301	75018-5123	111.50/4.390	102.50/4.035	110.00/4.331	96.62/3.804	120.40/4.740	92.00±0.08/3.622±.003	87.00±0.08/3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:  
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.  
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.  
CONTACTS: COPPER ALLOY  
HEXAGONAL THREADED INSERT: CARBON STEEL  
MACHINE SCREW: CARBON STEEL
- PLATING FINISH:  
CONTACT INTERFACE  
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD  
NICKEL UNDERPLATE OVERALL  
COMPLIANT INTERFACE  
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER  
NICKEL UNDERPLATE OVERALL  
HOUSING  
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER  
COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN.  
TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHKD BY: BARKER 2014/02/14 APPROV. BY: MILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	MM/IN	2:1	METRIC	☉
	▽=0	INCH				
	▽=0	4 PLACES ±.010 3 PLACES ±.025 2 PLACES ±.050 1 PLACE ±.100 0 PLACE ±.150				
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: BARKER 2014/02/14 APPROVED BY: MILLER 2014/03/13			
			MATERIAL NO. SEE TABLE SIZE D	DOCUMENT NO. SD-75126-2000		SHEET NO. 1 OF 2
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

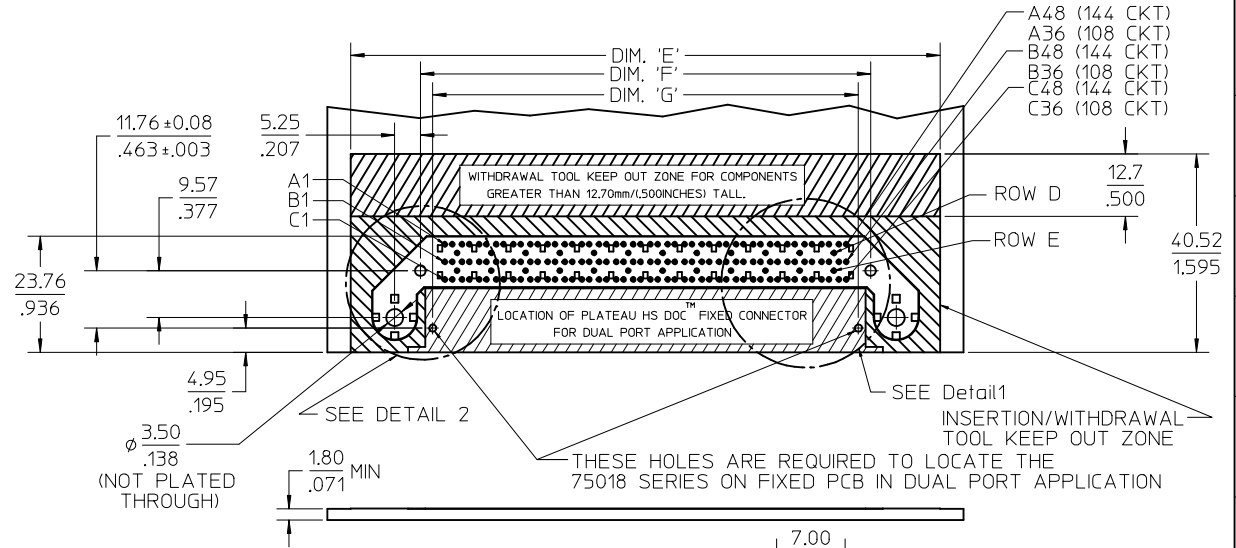
# KEEP OUT AREA FOR STAND-OFFS



APPLIES TO OTHER END ALSO

DETAIL2  
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

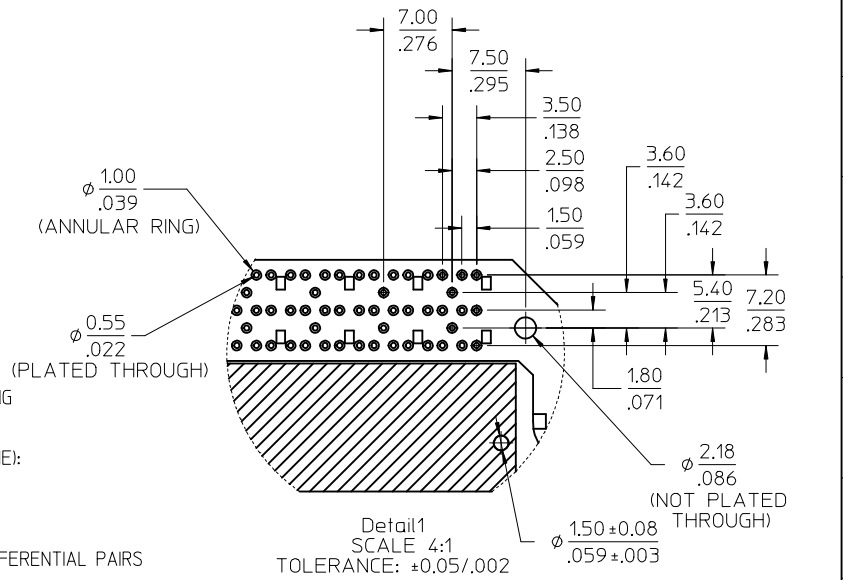


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):  
A2-A1: POWER/RETURN,  
A4-A3: POWER/RETURN,  
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS  
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E



Detail1  
SCALE 4:1

TOLERANCE: ±0.05/±.002

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: T1BARRA 2014/02/13 CHECKED BY: BBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DATE	DATE	TITLE	
	▽=0	3 PLACES ± .025	2014/02/13	2014/02/14	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	1 PLACE ± .010	0 PLACE ± .010	APPROVED BY	DATE		
	ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SMILLER 2014/03/13			
	MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SD-75126-2000	SHEET NO.	2 OF 2
	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				